Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
21.1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type			Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information			
Supplier Information													
mpany name* Company unique ID				Unique ID Authority					Response Date*				
ni										2024-05-09			
Contact Name	Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com						
nthorized Representative*  Title - Representative				Phone - Representative*			Email - Representative*						
Product-Env-Stewards Product Enviro Compliance		o Compliance		NA			Product-Env-Stewards@onsemi.com						
Requester Item Number Mfr Ite	Mfr Item Number Mfr		Mfr Item Name		Effective Dat	e Versio	n	Manufacturing Site		V	Veight*	UOM	Unit Type
AR033 A0-CP	0CM1C21SHK	3 MP 1/3 CIS			2024-05-09			CP2		5	7.72	mg	Each
Manufacturing Process Information													
Terminal Plating / Grid Array Material	Terminal Base A	erminal Base Alloy J-STD-(		Rating	Peak Pro	Peak Process Body Temperature Ma		ure Max Ti	me at Peak	Temperatu	re Num	ber of Reflow Cyc	eles
SnAgCu	CU Alloy	5			260		С	30		second	ls 3		
Comments													
or more information regarding material compositio	n please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led				
Pointective 2015/863/EU amending RoHS Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the co	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit iden you believe may apply. If the part is an assemble is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted				
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per	the definition above except for defined Ro	oHS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the				
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.53	mg		Misc.	proprietary data		0.0362	mg
			Supplier	Silicon (Si)	7440-21-3		9.3994	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0943	mg
Die Attach	0.91	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.3413	mg
			Supplier	Ethylene Glycol	107-21-1		0.0091	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0273	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.1911	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3413	mg
Electrode	0.97	mg	Supplier	Titanium (Ti)	7440-32-6		0.0006	mg
			В	Nickel (Ni)	7440-02-0		0.5775	mg
			Supplier	Gold (Au)	7440-57-5		0.0233	mg
			Supplier	Copper (Cu)	7440-50-8		0.0146	mg
			Supplier	Aluminum (Al)	7429-90-5		0.354	mg
Glass Lid /Cap	40.57	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		5.7609	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		20.285	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		9.7368	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		4.4627	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.0406	mg
			В	Arsenic Trioxide (As2O3)	1327-53-3		0.284	mg
Lid Attach	0.01	mg		Photoinitiator	proprietary data		0.0025	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0075	mg
Passivation	0.91	mg	Supplier	Pentaerythritol triacrylate	3524-68-3		0.1365	mg
			Supplier	2-(2-methoxypropoxy)propanol	34590-94-8		0.091	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.091	mg
			Supplier	9-Phenylacridine	602-56-2		0.0455	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.546	mg
Solder Ball	0.71	mg	Supplier	Silver (Ag)	7440-22-4		0.0543	mg
			Supplier	Tin (Sn)	7440-31-5		0.6397	mg
			Supplier	Copper (Cu)	7440-50-8		0.016	mg
Substrate and Solder Mask	4.11	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.411	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		1.9523	mg

Supplier	Bismaleimide Triazine resin	Proprietary Data	1.7468 mg	g